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Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256gm604-i-pt

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
OC1CON1	0900	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000	
OC1CON2	0902	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	0000	
OC1RS	0904	Output Compare 1 Secondary Register																	xxxx
OC1R	0906	Output Compare 1 Register																	xxxx
OC1TMR	0908	Output Compare 1 Timer Value Register																	xxxx
OC2CON1	090A	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000	
OC2CON2	090C	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	0000	
OC2RS	090E	Output Compare 2 Secondary Register																	xxxx
OC2R	0910	Output Compare 2 Register																	xxxx
OC2TMR	0912	Output Compare 2 Timer Value Register																	xxxx
OC3CON1	0914	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000	
OC3CON2	0916	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	0000	
OC3RS	0918	Output Compare 3 Secondary Register																	xxxx
OC3R	091A	Output Compare 3 Register																	xxxx
OC3TMR	091C	Output Compare 3 Timer Value Register																	xxxx
OC4CON1	091E	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000	
OC4CON2	0920	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	0000	
OC4RS	0922	Output Compare 4 Secondary Register																	xxxx
OC4R	0924	Output Compare 4 Register																	xxxx
OC4TMR	0926	Output Compare 4 Timer Value Register																	xxxx
OC5CON1	0928	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000	
OC5CON2	092A	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	0000	
OC5RS	092C	Output Compare 5 Secondary Register																	xxxx
OC5R	092E	Output Compare 5 Register																	xxxx
OC5TMR	0930	Output Compare 5 Timer Value Register																	xxxx
OC6CON1	0932	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000	
OC6CON2	0934	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	0000	
OC6RS	0936	Output Compare 6 Secondary Register																	xxxx
OC6R	0938	Output Compare 6 Register																	xxxx
OC6TMR	093A	Output Compare 6 Timer Value Register																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-35: NVM REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0728	WR	WREN	WRERR	NVMSIDL	—	—	RPDF	URERR	—	—	—	—	NVMOP3	NVMOP2	NVMOP1	NVMOP0	0000
NVMADR	072A	NVMADR<15:0>																0000
NVMADRU	072C	—	—	—	—	—	—	—	—	NVMADRU<23:16>								0000
NVMKEY	072E	—	—	—	—	—	—	—	—	NVMKEY<7:0>								0000
NVMSRCADR1	0730	NVMSRCADR<15:1>															0	0000
NVMSRCADRH	0732									NVMSRCADRH<23:16>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-36: SYSTEM CONTROL REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	—	—	VREGSF	—	CM	VREGS	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	Note 1
OSCCON	0742	—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0	CLKLOCK	IOLOCK	LOCK	—	CF	—	LPOSCEN	OSWEN	Note 2
CLKDIV	0744	ROI	DOZE2	DOZE1	DOZE0	DOZEN	FRCDIV2	FRCDIV1	FRCDIV0	PLLPOST1	PLLPOST0	—	PLLPRE4	PLLPRE3	PLLPRE2	PLLPRE1	PLLPRE0	0030
PLLFBD	0746	—	—	—	—	—	—	PLLDIV<8:0>										0030
OSCTUN	0748	—	—	—	—	—	—	—	—	—	TUN<5:0>							0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: RCON register Reset values are dependent on the type of Reset.

2: OSCCON register Reset values are dependent on the configuration fuses.

TABLE 4-37: REFERENCE CLOCK REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
REFOCON	074E	ROON	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.5.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

It is important to realize that the address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note: The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset (such as [W7 + W2]) is used, Modulo Addressing correction is performed, but the contents of the register remain unchanged.

4.6 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms; it is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.6.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled when all of these conditions are met:

- BWM bits (W register selection) in the MODCON register are any value other than '1111' (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last 'N' bits of the data buffer start address must be zeros.

XB<14:0> is the Bit-Reversed Addressing modifier, or 'pivot point', which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note: All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It does not function for any other addressing mode or for byte-sized data and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note: Modulo Addressing and Bit-Reversed Addressing can be enabled simultaneously using the same W register, but Bit-Reversed Addressing operation will always take precedence for data writes when enabled.

If Bit-Reversed Addressing has already been enabled by setting the BREN (XBREV<15>) bit, a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

4.7 Interfacing Program and Data Memory Spaces

The dsPIC33EPXXXGM3XX/6XX/7XX architecture uses a 24-bit-wide Program Space and a 16-bit-wide Data Space. The architecture is also a modified Harvard scheme, meaning that data can also be present in the Program Space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Aside from normal execution, the architecture of the dsPIC33EPXXXGM3XX/6XX/7XX devices provides two methods by which Program Space can be accessed during operation:

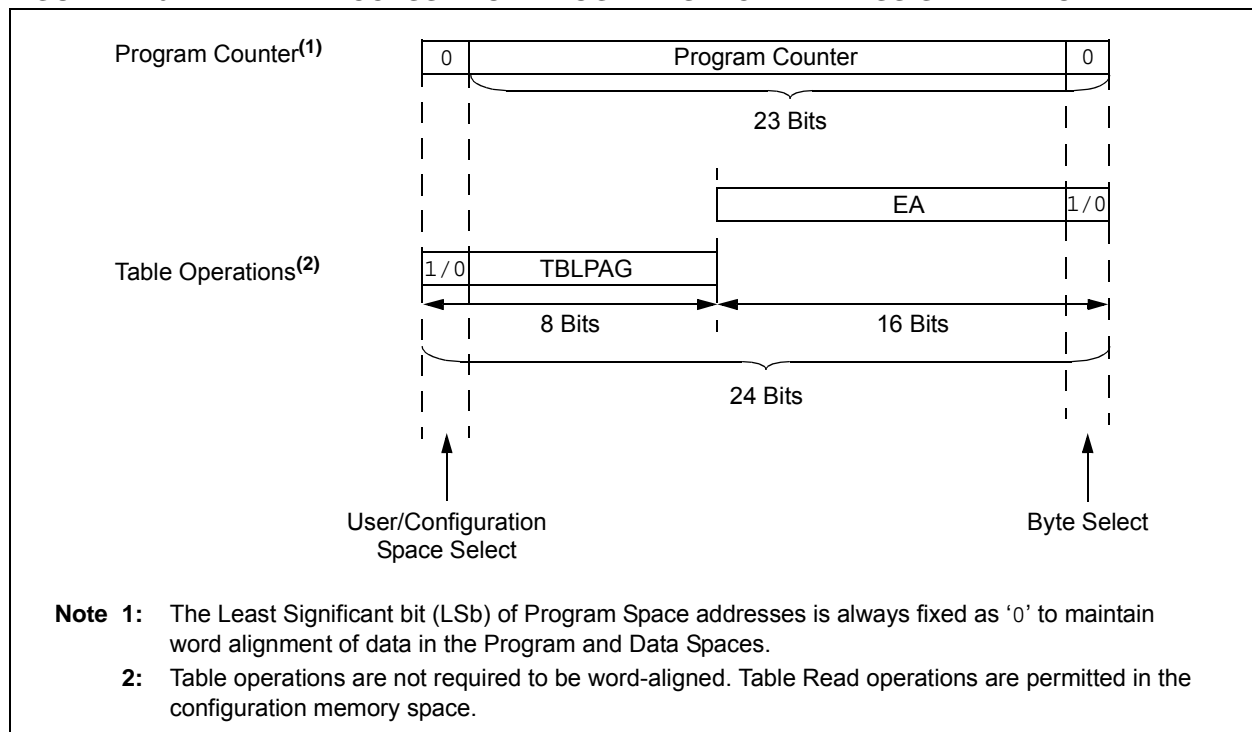
- Using table instructions to access individual bytes or words anywhere in the Program Space
- Remapping a portion of the Program Space into the Data Space (Program Space Visibility)

Table instructions allow an application to read or write to small areas of the program memory. This capability makes the method ideal for accessing data tables that need to be updated periodically. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for look-ups from a large table of static data. The application can only access the least significant word of the program word.

TABLE 4-68: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		

FIGURE 4-16: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



6.0 RESETS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the “dsPIC33/PIC24 Family Reference Manual”, “Reset” (DS70602), which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Reset module combines all Reset sources and controls the device Master Reset Signal, $\overline{\text{SYSRST}}$. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- MCLR: Master Clear Pin Reset
- SWR: RESET Instruction
- WDTO: Watchdog Timer Time-out Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
 - Illegal Opcode Reset
 - Illegal Address Mode Reset
 - Uninitialized W Register Reset
 - Security Reset

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of Reset will make the $\overline{\text{SYSRST}}$ signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state and some are unaffected.

Note: Refer to the specific peripheral section or **Section 4.0 “Memory Organization”** of this manual for register Reset states.

All types of device Reset set a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

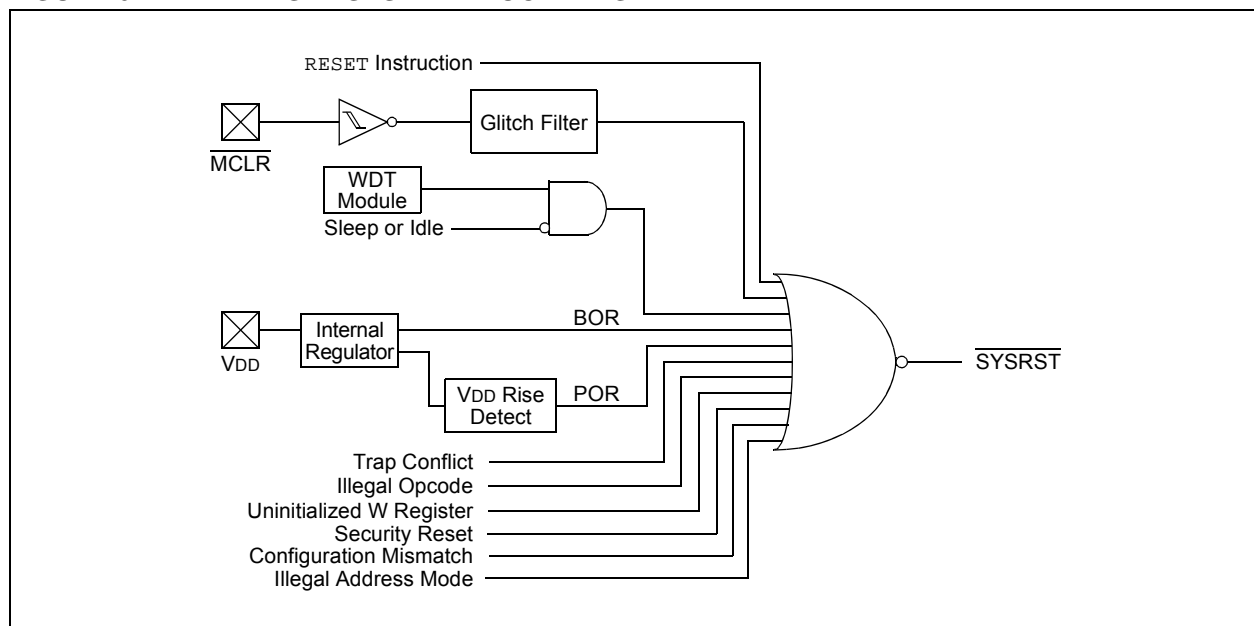
A POR clears all the bits, except for the POR and BOR bits (RCON<1:0>) that are set. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this manual.

Note: The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset is meaningful.

Note: In all types of Resets, to select the device clock source, the contents of OSCCON are initialized from the FNOSC_x Configuration bits in the FOSCSEL Configuration register.

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM



dsPIC33EPXXXGM3XX/6XX/7XX

FIGURE 7-1: dsPIC33EPXXXGM3XX/6XX/7XX INTERRUPT VECTOR TABLE

Reset – GOTO Instruction	0x000000
Reset – GOTO Address	0x000002
Oscillator Fail Trap Vector	0x000004
Address Error Trap Vector	0x000006
Generic Hard Trap Vector	0x000008
Stack Error Trap Vector	0x00000A
Math Error Trap Vector	0x00000C
DMA Controller Error Trap Vector	0x00000E
Generic Soft Trap Vector	0x000010
Reserved	0x000012
Interrupt Vector 0	0x000014
Interrupt Vector 1	0x000016
:	:
:	:
:	:
Interrupt Vector 52	0x00007C
Interrupt Vector 53	0x00007E
Interrupt Vector 54	0x000080
:	:
:	:
:	:
Interrupt Vector 116	0x0000FC
Interrupt Vector 117	0x0000FE
Interrupt Vector 118	0x000100
Interrupt Vector 119	0x000102
Interrupt Vector 120	0x000104
:	:
:	:
:	:
Interrupt Vector 244	0x0001FC
Interrupt Vector 245	0x0001FE
START OF CODE	0x000200

Decreasing Natural Order Priority

IVT

See Table 7-1 for Interrupt Vector Details

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REGISTER 8-11: DMAPWC: DMA PERIPHERAL WRITE COLLISION STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-4 **Unimplemented:** Read as '0'

bit 3 **PWCOL3:** Channel 3 Peripheral Write Collision Flag bit

1 = Write collision is detected

0 = No write collision is detected

bit 2 **PWCOL2:** Channel 2 Peripheral Write Collision Flag bit

1 = Write collision is detected

0 = No write collision is detected

bit 1 **PWCOL1:** Channel 1 Peripheral Write Collision Flag bit

1 = Write collision is detected

0 = No write collision is detected

bit 0 **PWCOL0:** Channel 0 Peripheral Write Collision Flag bit

1 = Write collision is detected

0 = No write collision is detected

12.1 Timer1 Control Register

REGISTER 12-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON ⁽¹⁾	—	TSIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
—	TGATE	TCKPS1	TCKPS1	—	TSYNC ⁽¹⁾	TCS ⁽¹⁾	—
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15 **TON:** Timer1 On bit⁽¹⁾
1 = Starts 16-bit Timer1
0 = Stops 16-bit Timer1
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **TSIDL:** Timer1 Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode
- bit 12-7 **Unimplemented:** Read as '0'
- bit 6 **TGATE:** Timer1 Gated Time Accumulation Enable bit
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled
- bit 5-4 **TCKPS<1:0>:** Timer1 Input Clock Prescale Select bits
11 = 1:256
10 = 1:64
01 = 1:8
00 = 1:1
- bit 3 **Unimplemented:** Read as '0'
- bit 2 **TSYNC:** Timer1 External Clock Input Synchronization Select bit⁽¹⁾
When TCS = 1:
1 = Synchronizes external clock input
0 = Does not synchronize external clock input
When TCS = 0:
This bit is ignored.
- bit 1 **TCS:** Timer1 Clock Source Select bit⁽¹⁾
1 = External clock is from pin, T1CK (on the rising edge)
0 = Internal clock (Fp)
- bit 0 **Unimplemented:** Read as '0'

Note 1: When Timer1 is enabled in External Synchronous Counter mode (TCS = 1, TSYNC = 1, TON = 1), any attempts by user software to write to the TMR1 register are ignored.

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REGISTER 27-3: ALCFGRPT: ALARM CONFIGURATION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **ALRMEN:** Alarm Enable bit

1 = Alarm is enabled (cleared automatically after an alarm event whenever ARPT<7:0> = 0x00 and CHIME = 0)

0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit

1 = Chime is enabled; ARPT<7:0> bits are allowed to roll over from 0x00 to 0xFF

0 = Chime is disabled; ARPT<7:0> bits stop once they reach 0x00

bit 13-10 **AMASK<3:0>:** Alarm Mask Configuration bits

0000 = Every half second

0001 = Every second

0010 = Every 10 seconds

0011 = Every minute

0100 = Every 10 minutes

0101 = Every hour

0110 = Once a day

0111 = Once a week

1000 = Once a month

1001 = Once a year (except when configured for February 29th, once every 4 years)

101x = Reserved – do not use

11xx = Reserved – do not use

bit 9-8 **ALRMPTR<1:0>:** Alarm Value Register Window Pointer bits

Points to the corresponding Alarm Value registers when reading the ALRMVAL register. The ALRMPTR<1:0> value decrements on every read or write of ALRMVAL until it reaches '00'.

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits

11111111 = Alarm will repeat 255 more times

•

•

•

00000000 = Alarm will not repeat

The counter decrements on any alarm event. The counter is prevented from rolling over from 0x00 to 0xFF unless CHIME = 1.

REGISTER 28-1: PMCON: PARALLEL MASTER PORT CONTROL REGISTER⁽³⁾ (CONTINUED)

bit 3	CS1P: Chip Select 0 Polarity bit ⁽¹⁾ 1 = Active-high (PMCS1/PMCS) ⁽²⁾ 0 = Active-low (PMCS1/PMCS)
bit 2	BEP: Byte Enable Polarity bit 1 = Byte enable is active-high (PMBE) 0 = Byte enable is active-low (PMBE)
bit 1	WRSP: Write Strobe Polarity bit <u>For Slave Modes and Master Mode 2 (PMMODE<9:8> = 00, 01, 10):</u> 1 = Write strobe is active-high (PMWR) 0 = Write strobe is active-low (PMWR) <u>For Master Mode 1 (PMMODE<9:8> = 11):</u> 1 = Enables strobe active-high (PMENB) 0 = Enables strobe active-low (PMENB)
bit 0	RDSP: Read Strobe Polarity bit <u>For Slave Modes and Master Mode 2 (PMMODE<9:8> = 00, 01, 10):</u> 1 = Read strobe is active-high (PMRD) 0 = Read strobe is active-low (PMRD) <u>For Master Mode 1 (PMMODE<9:8> = 11):</u> 1 = Enables strobe active-high (PMRD/PMWR) 0 = Enables strobe active-low (PMRD/PMWR)

- Note 1:** These bits have no effect when their corresponding pins are used as address lines.
- 2:** PMCS1 applies to Master mode and PMCS applies to Slave mode.
- 3:** This register is not available on 44-pin devices.

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REGISTER 28-2: PMMODE: PARALLEL MASTER PORT MODE REGISTER⁽⁴⁾

R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUSY	IRQM1	IRQM0	INCM1	INCM0	MODE16	MODE1	MODE0
bit 15						bit 8	

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAITB1 ^(1,2,3)	WAITB0 ^(1,2,3)	WAITM3	WAITM2	WAITM1	WAITM0	WAITE1 ^(1,2,3)	WAITE0 ^(1,2,3)
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at Reset

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **BUSY:** Busy bit (Master mode only)

1 = Port is busy

0 = Port is not busy

bit 14-13 **IRQM<1:0>:** Interrupt Request Mode bits

11 = Interrupt is generated when Read Buffer 3 is read or Write Buffer 3 is written (Buffered PSP mode), or on a read/write operation when PMA<1:0> = 11 (Addressable PSP mode only)

10 = Reserved

01 = Interrupt is generated at the end of the read/write cycle

00 = No Interrupt is generated

bit 12-11 **INCM<1:0>:** Increment Mode bits

11 = PSP read and write buffers auto-increment (Legacy PSP mode only)

10 = Decrement ADDR by 1 every read/write cycle

01 = Increment ADDR by 1 every read/write cycle

00 = No increment or decrement of address

bit 10 **MODE16:** 8/16-Bit Mode bit

1 = 16-Bit Mode: Data register is 16 bits, a read/write to the Data register invokes two 8-bit transfers

0 = 8-Bit Mode: Data register is 8 bits, a read/write to the Data register invokes one 8-bit transfer

bit 9-8 **MODE<1:0>:** Parallel Slave Port Mode Select bits

11 = Master Mode 1 (PMCSx, PMRD/PMWR, PMENB, PMBE, PMA<x:0> and PMD<7:0>)

10 = Master Mode 2 (PMCSx, PMRD, PMWR, PMBE, PMA<x:0> and PMD<7:0>)

01 = Enhanced PSP, control signals (PMRD, PMWR, PMCSx, PMD<7:0> and PMA<1:0>)

00 = Legacy Parallel Slave Port, control signals (PMRD, PMWR, PMCSx and PMD<7:0>)

bit 7-6 **WAITB<1:0>:** Data Setup to Read/Write/Address Phase Wait State Configuration bits^(1,2,3)

11 = Data Wait of 4 TP (demultiplexed/multiplexed); address phase of 4 TP (multiplexed)

10 = Data Wait of 3 TP (demultiplexed/multiplexed); address phase of 3 TP (multiplexed)

01 = Data Wait of 2 TP (demultiplexed/multiplexed); address phase of 2 TP (multiplexed)

00 = Data Wait of 1 TP (demultiplexed/multiplexed); address phase of 1 TP (multiplexed)

Note 1: The applied Wait state depends on whether data and address are multiplexed or demultiplexed. See **Section 4.1.8 "Wait States"** in the **"Parallel Master Port (PMP)"** (DS70576) in the *"dsPIC33/PIC24 Family Reference Manual"* for more information.

2: WAITB<1:0> and WAITE<1:0> bits are ignored whenever WAITM<3:0> = 0000.

3: TP = 1/FP.

4: This register is not available on 44-pin devices.

30.6 JTAG Interface

dsPIC33EPXXXGM3XX/6XX/7XX devices implement a JTAG interface, which supports boundary scan device testing. Detailed information on this interface is provided in future revisions of the document.

Note: Refer to the “dsPIC33/PIC24 Family Reference Manual”, “**Programming and Diagnostics**” (DS70608) for further information on usage, configuration and operation of the JTAG interface.

30.7 In-Circuit Serial Programming

The dsPIC33EPXXXGM3XX/6XX/7XX devices can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the “dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits” (DS70663) for details about In-Circuit Serial Programming (ICSP).

Any of the three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

30.8 In-Circuit Debugger

When MPLAB® ICD 3 or the REAL ICE™ in-circuit emulator is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB X IDE. Debugging functionality is controlled through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to MCLR, VDD, VSS and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins (PGECx and PGEDx).

30.9 Code Protection and CodeGuard™ Security

The dsPIC33EPXXXGM3XX/6XX/7XX devices offer basic implementation of CodeGuard Security that supports only General Segment (GS) security. This feature helps protect individual Intellectual Property.

Note: Refer to the “dsPIC33/PIC24 Family Reference Manual”, “**CodeGuard™ Security**” (DS70634) for further information on usage, configuration and operation of CodeGuard Security.

TABLE 33-9: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	Typ. ⁽²⁾	Max.	Doze Ratio	Units	Conditions		
Doze Current (IDOZE) ⁽¹⁾							
DC73a	20	53	1:2	mA	-40°C	3.3V	70 MIPS
DC73g	8	30	1:128	mA			
DC70a	19	53	1:2	mA	+25°C	3.3V	60 MIPS
DC70g	8	30	1:128	mA			
DC71a	20	53	1:2	mA	+85°C	3.3V	60 MIPS
DC71g	10	30	1:128	mA			
DC72a	25	42	1:2	mA	+125°C	3.3V	50 MIPS
DC72g	12	30	1:128	mA			

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as outputs and driving low
- MCLR = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating or being clocked (defined PMDx bits are all ones)
- CPU executing

```
while(1)
{
NOP( );
}
```
- JTAG is disabled

2: Data in the "Typical" column is at 3.3V, +25°C unless otherwise specified.

dsPIC33EPXXXGM3XX/6XX/7XX

FIGURE 33-8: OUTPUT COMPARE x (OCx) TIMING CHARACTERISTICS

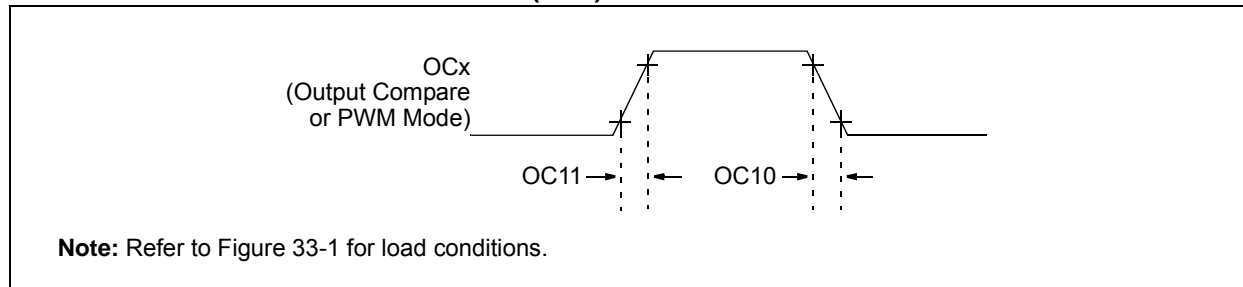


TABLE 33-26: OUTPUT COMPARE x (OCx) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 33-9: OCx/PWMx MODULE TIMING CHARACTERISTICS

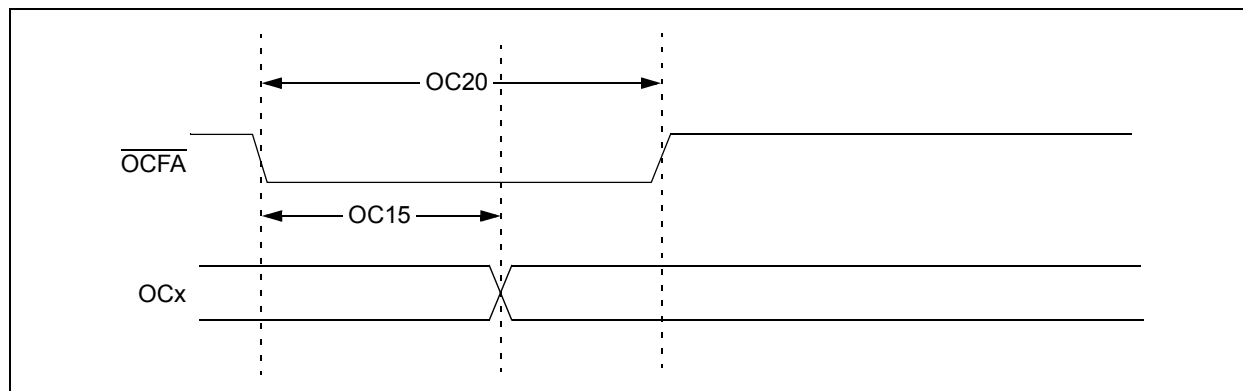


TABLE 33-27: OCx/PWMx MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
OC15	TfD	Fault Input to PWMx I/O Change	—	—	Tcy + 20	ns	
OC20	TfLT	Fault Input Pulse Width	Tcy + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 33-12: TIMERQ (QEIX MODULE) EXTERNAL CLOCK TIMING CHARACTERISTICS

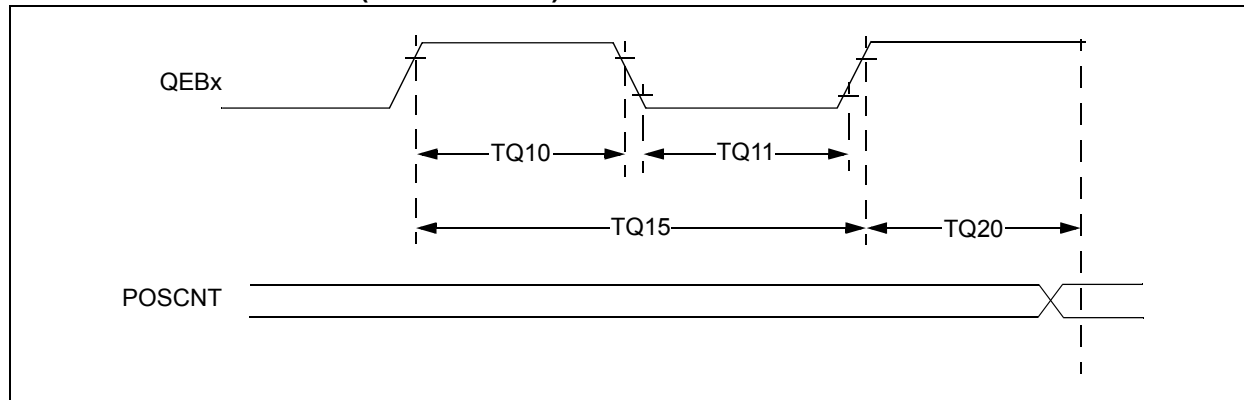


TABLE 33-29: QEIX MODULE EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾		Min.	Typ.	Max.	Units	Conditions
TQ10	TtQH	TQCK High Time	Synchronous, with Prescaler	Greater of: $12.5 + 25$ or $(0.5 T_{CY}/N) + 25$	—	—	ns	Must also meet Parameter TQ15
TQ11	TtQL	TQCK Low Time	Synchronous, with Prescaler	Greater of: $12.5 + 25$ or $(0.5 T_{CY}/N) + 25$	—	—	ns	Must also meet Parameter TQ15
TQ15	TtQP	TQCP Input Period	Synchronous, with Prescaler	Greater of: $25 + 50$ or $(1 T_{CY}/N) + 50$	—	—	ns	
TQ20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	T_{CY}	—	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 34-5: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T _A ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
HDC40e	3.6	8	mA	+150°C	3.3V	10 MIPS
HDC42e	5	15	mA	+150°C	3.3V	20 MIPS
HDC44e	10	20	mA	+150°C	3.3V	40 MIPS

TABLE 34-6: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T _A ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
HDC20	11	25	mA	+150°C	3.3V	10 MIPS
HDC22	15	30	mA	+150°C	3.3V	20 MIPS
HDC23	21	50	mA	+150°C	3.3V	40 MIPS

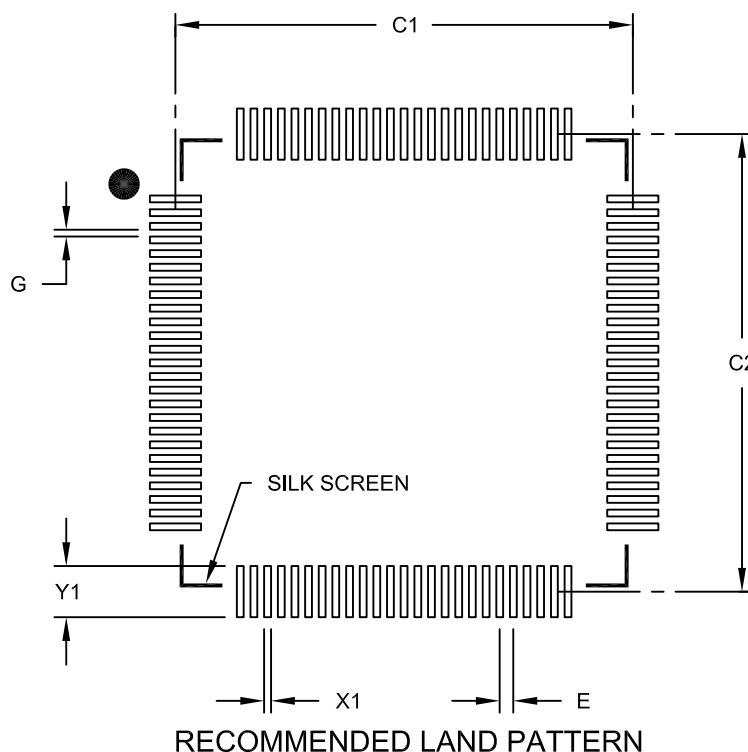
TABLE 34-7: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T _A ≤ +150°C			
Parameter No.	Typical	Max	Doze Ratio	Units	Conditions	
HDC72a	25	45	1:2	mA	+150°C	3.3V
HDC72g ⁽¹⁾	14	33	1:128	mA		

Note 1: Parameters with Doze ratios of 1:64 and 1:128 are characterized, but are not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PT)- 12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

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dsPIC33EPXXXGM3XX/6XX/7XX

NOTES:

Note the following details of the code protection feature on Microchip devices:

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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ISBN: 978-1-63276-507-9

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